



# Physical Design Analysis

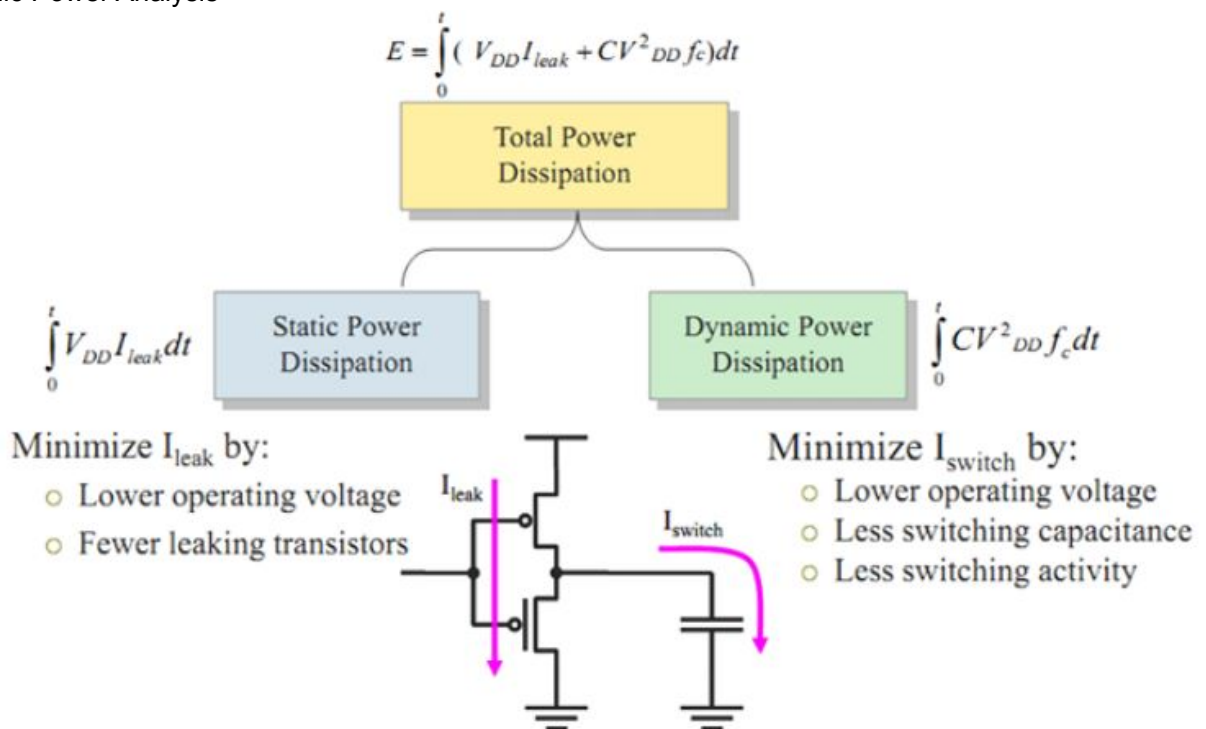
## Power Analysis

- Power Density of the Integrated Circuit increase exponentially with every Technology generation

$$P_{\text{TOTAL}} = P_{\text{DYNAMIC}} + P_{\text{LEAKAGE}}$$

$$P_{\text{DYNAMIC}} = P_{\text{SWITCHING}} + P_{\text{SHORT\_CIRCUIT}}$$

- Leakage Power (Static Power):** Leakage at almost all junctions due to various effects
  - Reverse Biased Diode Leakage
  - Gate Induced Drain Leakage
  - Gate Oxide Tunnelling
  - Sub-threshold Leakage
- Switching Power:** When signal change their state, energy is drawn from the power supply to charge up the loadcapacitance from 0 to VDD
- Short Circuit Power (Crowbar Power/ EM Rush Through Power):** Finite non-zero rise and fall times of transistors which causes a direct current path between the Power and Ground`
- Static/ Leakage Power Analysis
- Dynamic Power Analysis



- With Shrinking technology Static leakage increases which results in more focus in Reducing leakage power for advanced technologies

## Static Power/ Leakage Power

- It is the power consumed when the device is powered up but no signals are changing value (when the transistors are not switching)
- In CMOS devices, static power consumption is due to leakage
- Sub-threshold leakage occurs when a CMOS gate is not turned completely OFF

$$I_{SUB} = \mu C_{ox} V_{th}^2 \frac{W}{L} \cdot e^{-\frac{V_{GS}-V_T}{nV_{th}}}$$

where

$\mu$  - Carrier mobility

**COX** - Gate capacitance

**VT** - Threshold voltage

**VGS** - Gate-Source voltage

**W and L** - Dimensions of the transistor

**VTH** - Thermal voltage,  $kT/q = 25.9\text{mV}$  at room temperature

**n** - function of device fabrication process (ranges 1.0 -2.5)

**Static Power Dissipation** — Leakage Power, is consumed when the transistors are not switching

- Dependent on the voltage, temperature and state of the transistors
- Leakage Power =  $V \cdot I_{leak}$

### Types of Static Leakages

- Reverse biased diode leakage from the diffusion layers and the substrate
- Gate Induced Drain Leakage
- Gate Oxide Tunnelling
- Sub-threshold Leakage caused by reduced threshold voltages which prevents the Gate from completely turning OFF

### Static Power Reduction Techniques

- Using Multi VT cell in the design and optimizing for leakage by replacing high VT cell for non timing critical paths
- Power Gating
  - Power Shut-off groups of logic which are not used
- Voltage Scaling
- Multi VDD and Voltage Island
- Multi-threshold CMOS (Back Biasing)

### Dynamic/ Switching Power

- Dynamic power is the power consumed when the device is active, when signals are changing values (by switching logic states)
- Primary source of dynamic power consumption is switching power

$$P_{DYN} = A C V^2 F$$

where,

A is activity factor, i.e., the fraction of the circuit that is switching

C is Load capacitance

V is supply voltage

F is clock frequency

## Dynamic Power Calculation depends on

- Switching frequency
- Transition
- Output load
- Cell internal power **Dynamic Power Dissipation**
  - Dynamic power is dissipated any time the voltage on a net changes due to some stimulus

### Types of Dynamic Power

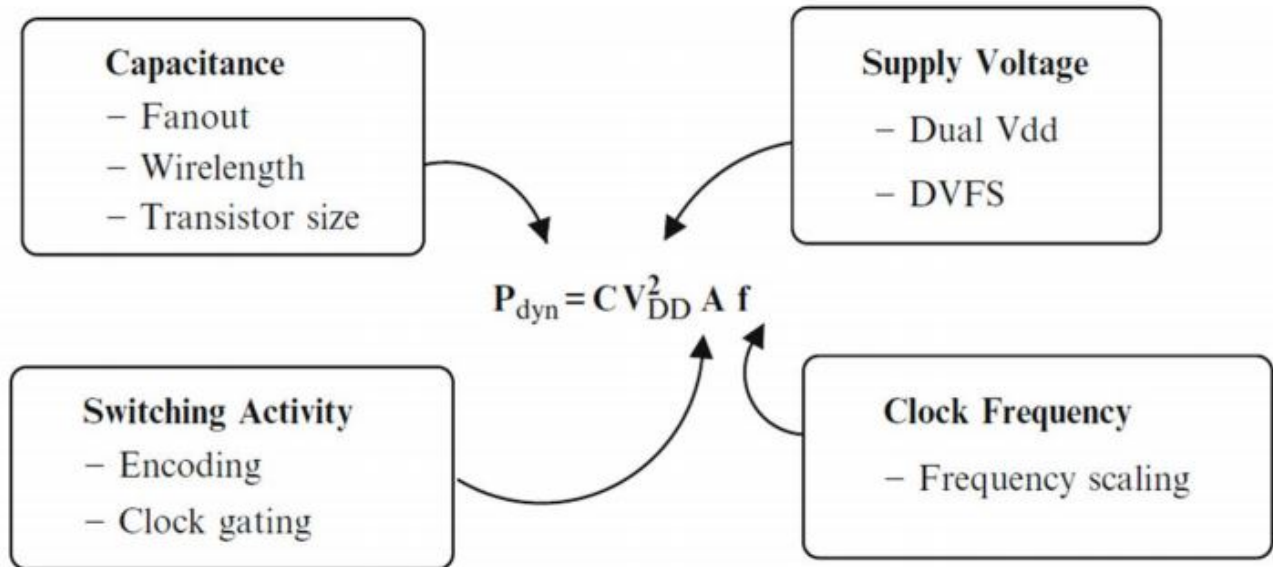
## Types of Dynamic Power

- Net Switching Power =  $(C_{int} * V * V * f)$
- Internal Power =  $(C_{int} * V * V * f) + (V * I_{sc})$

**Short Circuit :**  $= (V * I_{sc})$  During switching both PMOS and NMOS becomes on which results in a short circuit current

**Internal Capacitance Loading Power** =  $(C_{int} * V * V * f)$  is the power consumed while charging/discharging internal nets

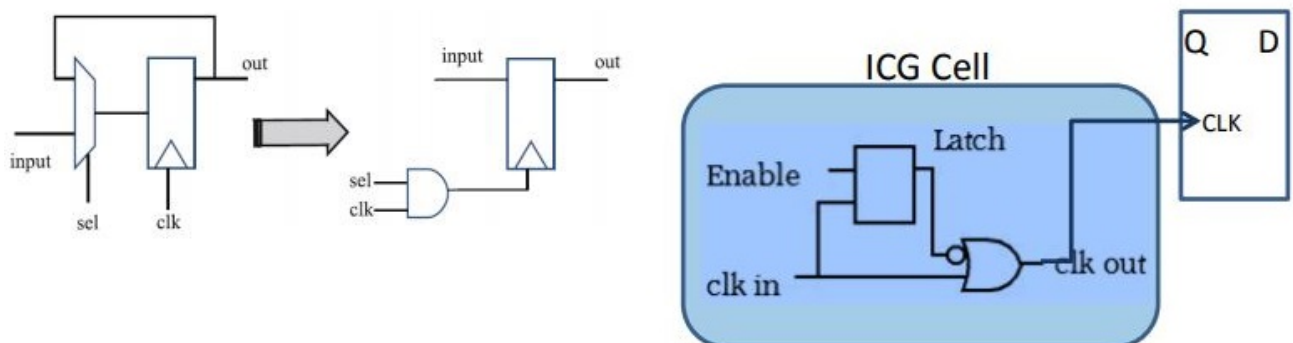
## Dynamic Power Reduction Techniques



## Dynamic Power Reduction Techniques

### Clock Gating

- Architectural Technique to reduce Dynamic Power along the Clock Path
- Clock gates should be placed at the Root of the Clock
- Results in small delay, more area and makes the design complex
- Clock Gating logic is generally in the form of "Integrated clock gating" (ICG)
- Sequential clock gating is the process of extracting/propagating the enable conditions to the upstream/downstream sequential elements, so that additional registers can be clock gated
- As the granularity on which you gate the clock of a synchronous circuit approaches zero, the power consumption of that circuit approaches that of an asynchronous circuit: the circuit only generates logic transitions when it is actively computing



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***VLSI BACK-END ADVENTURE***

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